A post chemical-mechanical-polishing (post-CMP) cleaning composition comprising a specific sulfur-containing compound and a sugar alcohol or a polycarboxylic acid

Abstract

A post chemical-mechanical-polishing (post-CMP) cleaning composition comprising:

(A) at least one compound comprising at least one thiol (–SH), thioether (–SR^1) or thiocarbonyl (>C=S) group, wherein R^1 is alkyl, aryl, alkylaryl or arylalkyl,

(B) at least one sugar alcohol which contains at least three hydroxyl (–OH) groups and does not comprise any carboxylic acid (–COOH) or carboxylate ($–COO^-$) groups, and

(C) an aqueous medium.

No suitable figure